



2814

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PTO/SB/21 (08-00)

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<b>TRANSMITTAL FORM</b> <i>(to be used for all correspondence after initial filing)</i>	<b>Application Number</b>	09/707,844	
	<b>Filing Date</b>	November 8, 2000	
	<b>First Named Inventor</b>	Hidetoshi ISHIDA et al.	
	<b>Group Art Unit</b>	2814	
	<b>Examiner Name</b>	Dana FARAHANI	
<b>Total Number of Pages in This Submission</b>	1	<b>Attorney Docket Number</b>	740819-448

ENCLOSURES (check all that apply)		
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Firm or Individual name	<u>Donald R. Studebaker (Reg. No. 32,815)</u> Nixon Peabody LLP 8180 Greensboro Drive Suite 800 McLean, VA 22102
Signature	
Date	August 28, 2002

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PATENT 740819-448

9/5/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: ) Group Art Unit: 2814  
Hidetoshi ISHIDA et al. ) Examiner: Dana FARAHANI  
Serial No. 09/707,844 )  
Filed: November 8, 2000 )  
For: SEMICONDUCTOR DEVICE )

AMENDMENT

Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

In response to the Examiner's non-final Office Action mailed May 29, 2002, please consider the following amendments and remarks in connection with the above-identified application.

IN THE CLAIMS:

Please amend claims 1 and 6 as follows:

1. (Amended) A semiconductor device comprising:  
a semiconductor substrate;  
at least two semiconductor components provided on the principal surface of the substrate; and  
multiple through holes, which pass from the principal surface through the backside of the substrate and are provided in a region of the substrate between the at least two components so as to substantially eliminate the electrical interference between the two semiconductor components.

6. (Amended) A semiconductor device comprising: